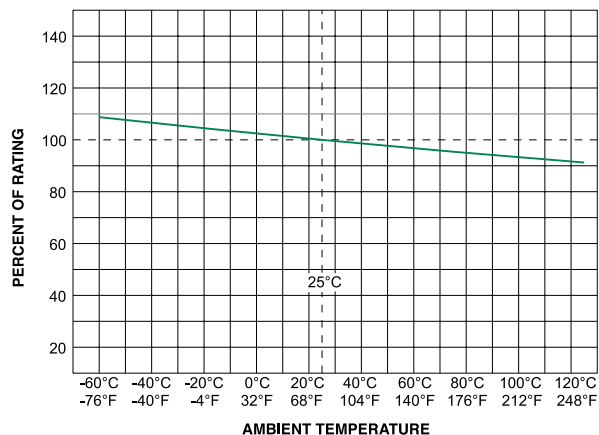
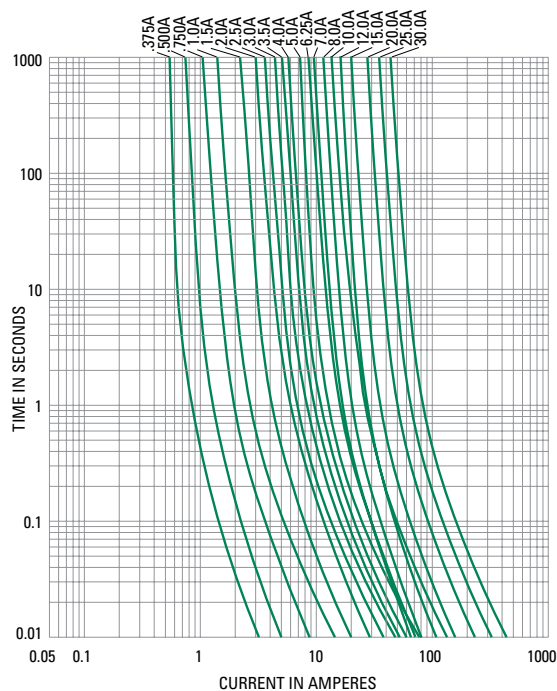


Temperature Re-rating Curve

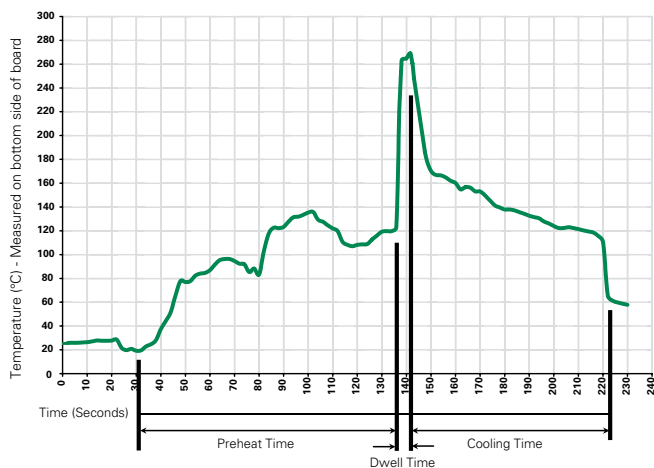


Note:
Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat:	
(Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C
Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.

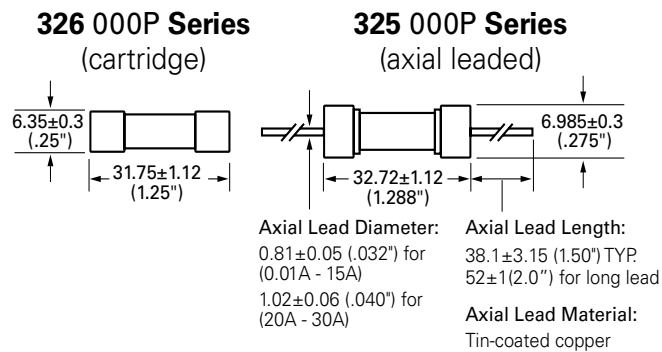
Product Characteristics

Materials	Body: Ceramic Cap: Nickel-plated brass Leads: Tin-plated Copper
Terminal Strength	MIL-STD-202, Method 211, Test Condition A
Solderability	MIL-STD-202 Method 208
Product Marking	Cap1: Brand logo, current and voltage ratings Cap2: Series and agency approval marks

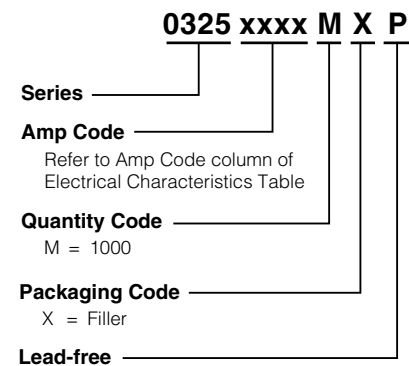
Operating Temperature	-55°C to +125°C
Thermal Shock	MIL-STD-202, Method 107, Test Condition B: (5 cycles - 65°C to 125°C)
Vibration:	MIL-STD-202, Method 201
Humidity	MIL-STD-202, Method 103, Test Condition A: High RH (95%) and Elevated temperature (40°C) for 240 hours
Salt Spray	MIL-STD-202, Method 101, Test Condition B

Dimensions

Measurements displayed in millimeters (inches)



Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Taping Width
325 Series				
Bulk	N/A	5	VX	N/A
Bulk	N/A	100	HX	N/A
Bulk	N/A	1000	MX	N/A
Bulk	N/A	1000	MX52 (long lead)	N/A
Bulk	N/A	1000	MX52L (long lead)	N/A
Bulk	N/A	1000	MXD	N/A
Bulk	N/A	1000	MXF31	N/A
Bulk	N/A	1000	MXW	N/A
326 Series				
Bulk	N/A	5	VX	N/A
Bulk	N/A	100	HX	N/A
Bulk	N/A	1000	MX	N/A
Bulk	N/A	1000	MXCC	N/A
Bulk	N/A	1000	MXD	N/A